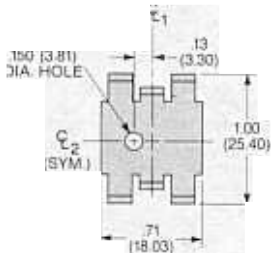
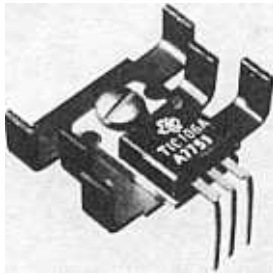
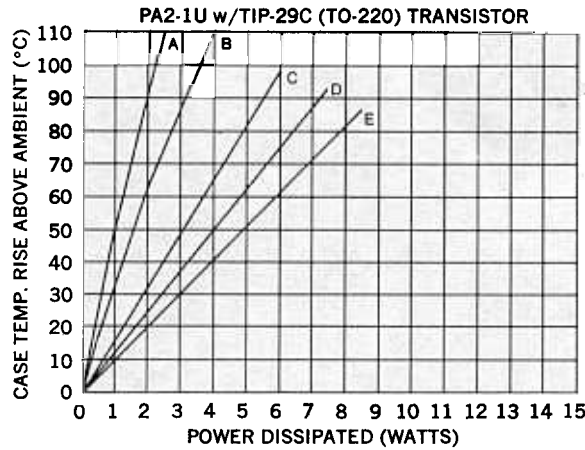


### PA2 Series



Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.



#### DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C. Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

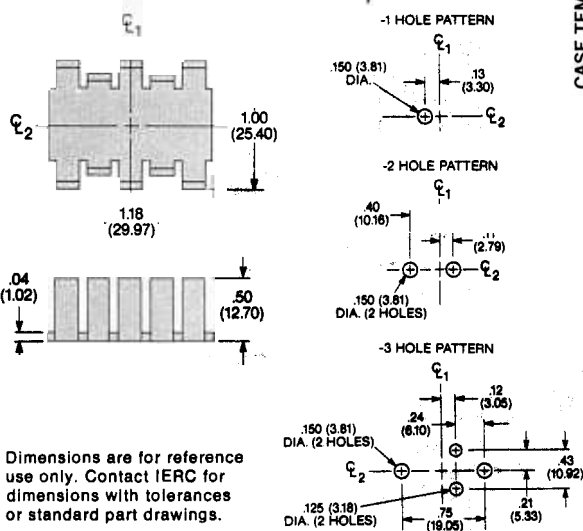
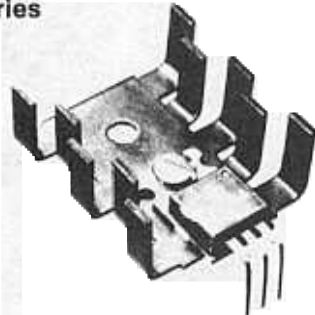
- Thermal Resistance Case to Sink is 0.9-1.1 °C/W w/Joint Compound.
- Uprate 2.4 °C/watt for black part in natural convection only.
- Derate 0.6 °C/watt for Insulube® part in natural convection only.

#### Ordering Information

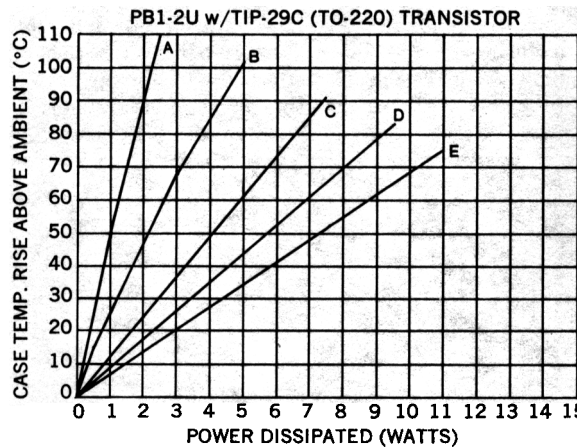
IERC PART NO.				Semiconductor Accommodated	Max. Weight (Grams)
Unplated	Com'l. Black Anodize	Mil. Black Anodize	Insulube® 448		
PA2U	PA2CB	PA2B	PA2	Undrilled TO-126, TO-127, TO-220	1.5
PA2-1U	PA2-1CB	PA2-1B	PA2-1		

Note: See page iv for other finishes.

### PB1 Series



Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.



#### DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C. Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

- Thermal Resistance Case to Sink is 0.9-1.1 °C/W w/Joint Compound.
- Uprate 2.4 °C/watt for black part in natural convection only.
- Derate 0.6 °C/watt for Insulube® part in natural convection only.

#### Ordering Information

IERC PART NO.				Semiconductor Accommodated	Max. Weight (Grams)
Unplated	Com'l. Black Anodize	Mil. Black Anodize	Insulube® 448		
PB1U	PB1CB	PB1B	PB1	Undrilled One TO-126, TO-127 or TO-220	3.0
PB1-1U	PB1-1CB	PB1-1B	PB1-1		
PB1-2U	PB1-2CB	PB1-2B	PB1-2	One or two TO-126, TO-127 or TO-220	3.0
PB1-3U	PB1-3CB	PB1-3B	PB1-3		

Note: See page iv for other finishes.